

Linear Products Die

Part Number	Description	Die Size (mils)	Bond Pad Metalization	Packaging
<i>Automotive Grade</i>				
AD8202WYC-P3	High common-mode voltage difference amp	47 × 46	AlCu	Reel
AD8202WYC-P7	High common-mode voltage difference amp	47 × 46	AlCu	Reel
AD8210WYC-P3	High speed, bidirectional current shunt amp	60 × 50	AlCu	Reel
AD8694WAC-P3	Low noise, CMOS op amp	57 × 53	AlCu	Reel
AD8694WAC-P7	Low noise, CMOS op amp	57 × 53	AlCu	Reel
<i>Commercial Grade</i>				
AD532JCHIPS	Multiplier IC	116 × 70	AlCu	Waffle pack
AD534KCHIPS	Multiplier IC	80 × 102	AlCu	Waffle pack
AD536ASCHIPS	RMS-to-DC converter IC	83 × 135	AlCu	Waffle pack
AD538ACHIPS	Multiplier	194 × 129	AlCu	Waffle pack
AD596ACHIPS	Thermocouple chip	90 × 58	AlCu	Waffle pack
AD603ACHIPS	Variable gain op amp	72 × 93	AlCu	Waffle pack
AD605ACHIPS	Low noise, dual-channel VGA	70 × 117	AlCu	Waffle pack
AD620ACHIPS	Low power instrumentation amp	61 × 109	AlCu	Waffle pack
AD624ACHIPS	Low noise, precision in-amp	103 × 171	AlCu	Waffle pack
AD629AC-WP	High common-mode voltage difference amp	97 × 65	AlCu	Waffle pack
AD744JCHIPS	High speed, BiFET op amp	63 × 63	AlCu	Waffle pack
AD8001ACHIPS	High performance, low power video amp	38 × 41	AlCu	Waffle pack
AD8003ACHIPS	1.4 GHz op amp with disable chip	76 × 41	AlCu	Waffle pack
AD8009ACHIPS	1 GHz, 5500 V/μs, low distortion amp	37 × 40	AlCu	Waffle pack
AD8013ACHIPS	Triple, low power video op amp	48 × 74	AlCu	Waffle pack
AD8023ACHIPS	Triple, high output video amp	63 × 71	AlCu	Waffle pack
AD8032ACHIPS	Dual, 2.7 V, 80 MHz rail-to-rail op amp	35 × 61	AlCu	Waffle pack
AD8034ACHIPS	Dual, 85 MHz FET input amp	31 × 76	AlCu	Waffle pack
AD8036ACHIPS	240 MHz, clamped amp gain = 1	41 × 45	AlCu	Waffle pack
AD8037ACHIPS	350 MHz, clamped amp gain = 2	47 × 51	AlCu	Waffle pack
AD8042ACHIPS	Dual, 160 MHz rail-to-rail amp	46 × 65	AlCu	Waffle pack
AD8057ACHIPS	Single, low cost, 350 MHz op amp	32 × 37	AlCu	Waffle pack
AD8058ACHIPS	Dual, low cost, 350 MHz op amp	40 × 45	AlCu	Waffle pack
AD810ACHIPS	High speed, video op amp with disable	62 × 94	AlCu	Waffle pack
AD811ACHIPS	High performance, video op amp	62 × 98	AlCu	Waffle pack
AD813ACHIPS	Triple, low power video op amp	57 × 124	AlCu	Waffle pack
AD8138ACHIPS	500 MHz, low distortion difference op amp	44 × 45	AlCu	Waffle pack

Part Number	Description	Die Size (mils)	Bond Pad Metalization	Packaging
<i>Commercial Grade (cont'd)</i>				
AD822C-WP	Dual, single-supply, precision amp	71 × 91	AlCu	Waffle pack
AD8221AC-P7	Single, 30 V/36 V in-amp	88 × 62	AlCu	Reel
AD825ACHIPS	High speed, FET input op amp	42 × 69	AlCu	Waffle pack
AD827JCHIPS	High speed, low power, dual op amp	54 × 125	AlCu	Waffle pack
AD829JCHIPS	High speed, low noise, video op amp	54 × 67	AlCu	Waffle pack
AD841JCHIPS	Wideband, unity gain, stable op amp	67 × 99	AlCu	Waffle pack
AD843JCHIPS	35 MHz, CBFET, high speed op amp	67 × 102	AlCu	Waffle pack
AD844ACHIPS	60 MHz, 2000 V/μs, wideband op amp	77 × 96	AlCu	Waffle pack
AD845JCHIPS	Precision, 16 MHz, CBFET, high speed op amp	57 × 112	AlCu	Waffle pack
AD847JCHIPS	High speed, low power op amp	54 × 67	AlCu	Waffle pack
AD848JCHIPS	Low power, high speed op amp	54 × 67	AlCu	Waffle pack
AD9631ACHIPS	350 MHz, unity gain, op amp	47 × 51	AlCu	Waffle pack
ADR02ACHIPS	5 V, precision band gap reference	33 × 41	AlCu	Waffle pack
AMP01NBC	Low noise, bipolar precision in-amp	116 × 149	AlCu	Waffle pack
AMP04GBC	Unity gain, low power, bipolar in-amp	79 × 99	AlCu	Waffle pack
OP27NBC	Low noise, precision, bipolar op amp	66 × 95	AlCu	Waffle pack
OP37NBC	Low noise, precision, high speed op amp	70 × 95	AlCu	Waffle pack
OP400GBC	Quad, low power, low offset, bipolar op amp	123 × 181	AlCu	Waffle pack
OP42NBC	High speed, fast settling, precision op amp	74 × 97	AlCu	Waffle pack
OP467GBC	Quad, precision, high speed, low noise op amp	112 × 123	AlCu	Waffle pack
OP77NBC	Ultralow, offset voltage, precision op amp	57 × 93	AlCu	Waffle pack
REF43NBC	Precision, low power, 2.5 V reference	65 × 84	AlCu	Waffle pack
<i>Known Good Die Grade</i>				
AD8028-KGD-CHIP	Dual, high speed, rail-to-rail input/output amp	59 × 54	AlCu	Waffle pack
AD8065-KGD-CHIP	Single, 135 MHz, low noise, FET input amp	34 × 47	AlCu	Waffle pack
ADA4897-2-KGD	1 nV/√Hz, low power op amp	56 × 48	AlCu	Waffle pack
AD8202W-KGD-R7	High common-mode voltage difference amp	46 × 46	AlCu	Reel
<i>High Temperature Grade</i>				
AD8229-KGD-CHIPS	Ultralow noise, 210°C, in-amp	69 × 114	AlCu	Waffle pack
AD8634-KGD	High temperature, dual rail-to-rail amp	52 × 44	AlSiCu	Waffle pack
ADR225-KGD	High temperature, precision, 2.5 V reference	39 × 56	AlCu	Waffle pack

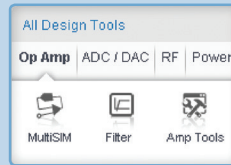
Part Number	Description	Die Size (mils)	Bond Pad Metalization	Packaging
<i>Military/Aerospace Grade</i>				
AD524SCHIPS	Precision, low noise in-amp	103 × 171	AlCu	Waffle pack
AD532SCHIPS	Multiplier IC	70 × 116	AlCu	Waffle pack
AD534SCHIPS	Multiplier IC	80 × 102	AlCu	Waffle pack
AD534TCHIPS	Multiplier IC	80 × 102	AlCu	Waffle pack
AD580TCHIPS	2.5 V reference	46 × 75	AlCu	Waffle pack
AD584TCHIPS	Programmable 10 V reference	63 × 89	AlCu	Waffle pack
AD624SCHIPS	Low noise, precision in-amp	103 × 171	AlCu	Waffle pack
AD630SCHIPS	Modulator/demodulator VGA	89 × 99	AlCu	Waffle pack
AD734SCHIPS	Multiplier IC	93 × 22	AlCu	Waffle pack
AD746SCHIPS	Dual, precision, BiFET op amp	70 × 110	AlCu	Waffle pack
AD811SCHIPS	High performance, video op amp	62 × 98	AlCu	Waffle pack
AD827SCHIPS	High speed, low power, dual op amp	54 × 125	AlCu	Waffle pack
AD829SCHIPS	High speed, low noise, video op amp	54 × 67	AlCu	Waffle pack
AD841SCHIPS	Wideband, unity gain, stable op amp	67 × 99	AlCu	Waffle pack
AD842SCHIPS	Wideband, high speed op amp	67 × 106	AlCu	Waffle pack
AD843SCHIPS	36 MHz, CBFET, high speed op amp	67 × 102	AlCu	Waffle pack
AD844SCHIPS	61 MHz, 2000 V/μs, wideband op amp	77 × 96	AlCu	Waffle pack
AD847SCHIPS	High speed, low power op amp	54 × 67	AlCu	Waffle pack
AD848SCHIPS	Low power, high speed op amp	54 × 67	AlCu	Waffle pack

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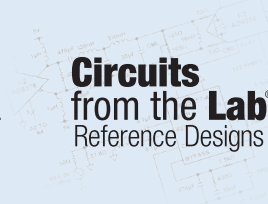
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For additional technical information, contact:

Asia Pacific: cic.asia@analog.com

EMEA: cic@analog.com

Japan: cic-japan@analog.com

North America: cic.americas@analog.com

Analog Devices, Inc. Worldwide Headquarters

Analog Devices, Inc.
One Technology Way
P.O. Box 9106
Norwood, MA 02062-9106
U.S.A.

Tel: 781.329.4700
(800.262.5643,
U.S.A. only)
Fax: 781.461.3113

Analog Devices, Inc. Europe Headquarters

Analog Devices, Inc.
Wilhelm-Wagenfeld-Str. 6
80807 Munich
Germany
Tel: 49.89.76903.0
Fax: 49.89.76903.157

Analog Devices, Inc. Japan Headquarters

Analog Devices, KK
New Pier Takeshiba
South Tower Building
1-16-1 Kaigan, Minato-ku,
Tokyo, 105-6891
Japan
Tel: 813.5402.8200
Fax: 813.5402.1064

Analog Devices, Inc. Asia Pacific Headquarters

Analog Devices
5F, Sandhill Plaza
2290 Zuchongzhi Road
Zhangjiang Hi-Tech Park
Pudong New District
Shanghai, China 201203
Tel: 86.21.2320.8000
Fax: 86.21.2320.8222